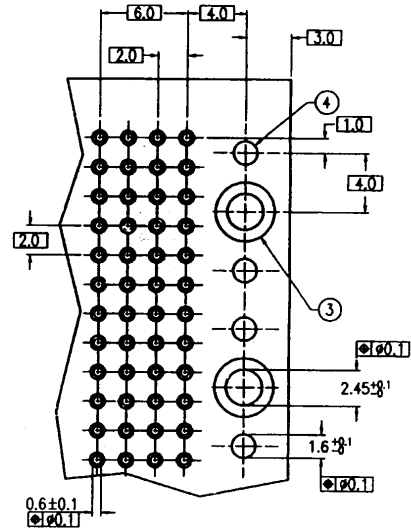
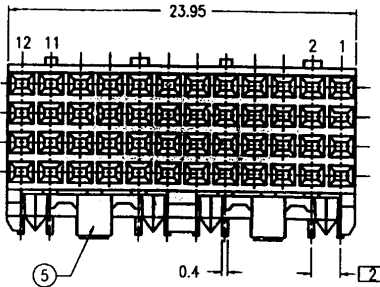
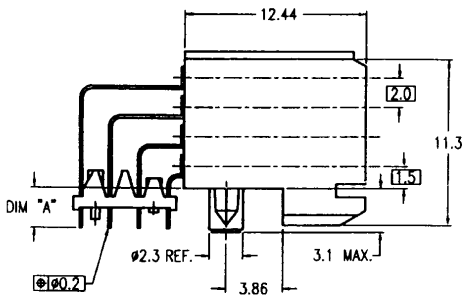


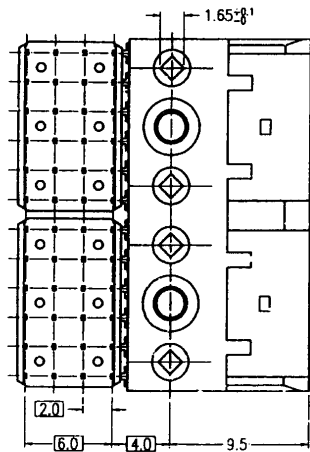
PRODUCT NO.	PLATING CONTACT AREA	UNDER PLATING
93337-1Y7	0.8μm GOLD	1.3μm Ni MIN.
93337-2Y7	2.0μm GOLD	1.3μm Ni MIN.
93337-3Y7	1.3μm GOLD	1.3μm Ni MIN.
93337-9Y7	0.8μm GXT	1.3μm Ni MIN.

PC BOARD VERSIONS		
PRODUCT NO.	PCB THICKNESS	DIM "A"
93337-X01	1.6	2.73
93337-X11	2.4	3.53

REVISIONS				
REV	DESCRIPTION	ECN	BY	DATE
A	RELEASED	J40231	S.S	7/21/94
B	REVISED	J80208	A.Y	9/9/98



RECOMMENDED P.C. BOARD LAY-OUT



NOTE

- 1 MATERIAL  
HOUSING : LCP UL94V-0  
CONTACT : PHOSPHOR BRONZE
- 2 PLATING  
SOLDER TAIL : Sn-Pb 2 ~8μm
- ③ PLATED THROUGH HOLES  
LAND SIZE :  $\phi 4 \pm 0.1$ mm  
(SQUARE LAND SIZE :  $\square 3$ mm)  
PLATING : Sn-Pb 10 ~15μm
- ④ UNPLATED THROUGH HOLES
- ⑤ DIP RING (2pcs.)  
MATERIAL : PHOSPHOR BRONZE t=0.15mm  
PLATING : Sn-Pb 2 ~3μm

SHEET INDEX	ISSUE	B										
	SH NO.	1										
TOLERANCES UNLESS OTHERWISE SPECIFIED			MAT	DR	DATE	CUSTOMER	TITLE					
±0.2			SEE NOTE 1. ⑤	S. Shio	7/21/94	COPY	METRAL R/A FEMALE SIGNAL					
LINEAR			FINISH	S. Yoshigawa	5/8/98	THIRD ANGLE PROJ	4X12 POS. DIP RING TYPE					
ANGLES			±2°	SEE NOTE 2. ⑤	APPRO	SCALE	SIZE	DWG. NO.	REV	SHEET		
					Ed. Amari	4/1	B	93337	B	1	of 1	

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ELECTRONICS

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